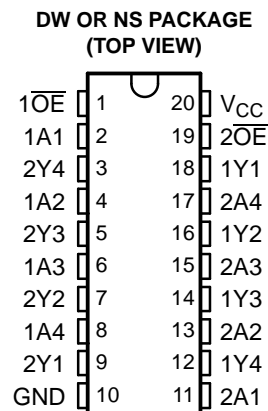


FEATURES

- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of up to -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree ⁽¹⁾
- 4.5-V to 5.5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 9.5 ns at 5 V
- Inputs Are TTL Compatible

(1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



DESCRIPTION/ORDERING INFORMATION

The SN74ACT244-EP octal buffer/driver is designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The device is organized as two 4-bit buffers/drivers with separate output-enable ($\overline{\text{OE}}$) inputs. When $\overline{\text{OE}}$ is low, the device passes noninverted data from the A inputs to the Y outputs. When $\overline{\text{OE}}$ is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

| T_{A} | PACKAGE ⁽¹⁾ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|--|------------------------|---------------|-----------------------|------------------|
| -55°C to 125°C | SOIC – DW | Tape and reel | SN74ACT244MDWREP | SACT244MEP |
| | SOP – NS | Tape and reel | SN74ACT244MNSREP | SACT244MEP |
| -40°C to 85°C | SOIC – DW | Tape and reel | SN74ACT244IDWREP | SACT244IEP |

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (EACH BUFFER)

| INPUTS | | OUTPUT Y |
|------------------------|---|-------------|
| $\overline{\text{OE}}$ | A | |
| L | H | H |
| L | L | L |
| H | X | Z |

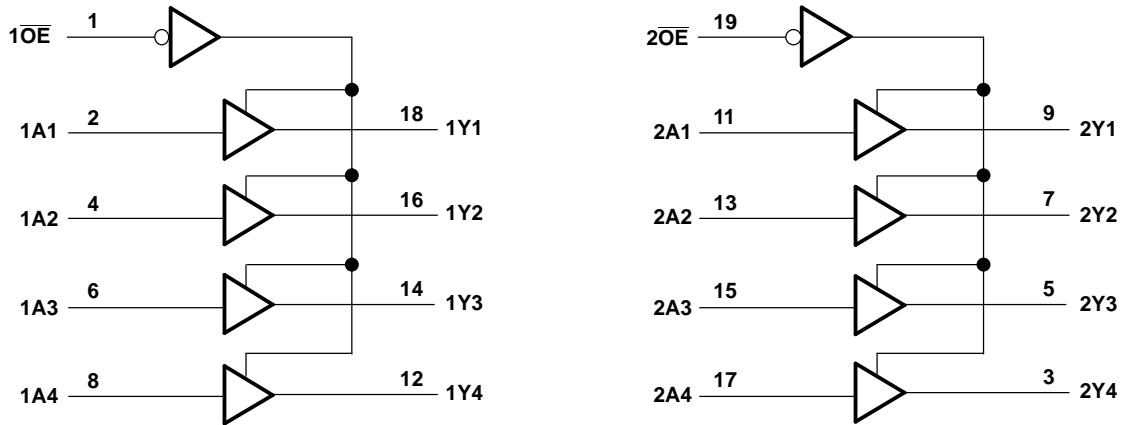


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SN74ACT244-EP OCTAL BUFFER/DRIVER WITH 3-STATE OUTPUTS

SCAS724B—OCTOBER 2003—REVISED MARCH 2006

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT |
|---------------|--|-----------------------------|----------------|--------------|
| V_{CC} | Supply voltage range | -0.5 | 7 | V |
| V_I | Input voltage range ⁽²⁾ | -0.5 | $V_{CC} + 0.5$ | V |
| V_O | Output voltage range ⁽²⁾ | -0.5 | $V_{CC} + 0.5$ | V |
| I_{IK} | Input clamp current | $V_I < 0$ or $V_I > V_{CC}$ | | ± 20 mA |
| I_{OK} | Output clamp current | $V_O < 0$ or $V_O > V_{CC}$ | | ± 20 mA |
| I_O | Continuous output current | $V_O = 0$ to V_{CC} | | ± 50 mA |
| | Continuous current through V_{CC} or GND | | | ± 200 mA |
| θ_{JA} | Package thermal impedance ⁽³⁾ | DW package | | 58 |
| | | NS package | | 60 |
| T_{stg} | Storage temperature range ⁽⁴⁾ | -65 | 150 | °C |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.
- (4) Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

Recommended Operating Conditions⁽¹⁾

| | | MIN | MAX | UNIT |
|---------------------|------------------------------------|----------------|----------|------|
| V_{CC} | Supply voltage | 4.5 | 5.5 | V |
| V_{IH} | High-level input voltage | 2 | | V |
| V_{IL} | Low-level input voltage | | 0.8 | V |
| V_I | Input voltage | 0 | V_{CC} | V |
| V_O | Output voltage | 0 | V_{CC} | V |
| I_{OH} | High-level output current | | -24 | mA |
| I_{OL} | Low-level output current | | 24 | mA |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | | 8 | ns/V |
| T_A | Operating free-air temperature | SN74ACT244M-EP | -55 | 125 |
| | | SN74ACT244I-EP | -40 | 85 |

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | T _A = 25°C | | | SN74ACT244M-EP | | SN74ACT244I-EP | | UNIT |
|---------------------------------|---|-----------------|-----------------------|------|-----|----------------|------|----------------|-----|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| V _{OH} | I _{OH} = -50 μA | 4.5 V | 4.4 | 4.49 | | 4.4 | | 4.4 | V | |
| | | 5.5 V | 5.4 | 5.49 | | 5.4 | | 5.4 | | |
| | I _{OH} = -24 mA | 4.5 V | 3.86 | | | 3.7 | 3.76 | | | |
| | | 5.5 V | 4.86 | | | 4.7 | 4.76 | | | |
| | I _{OH} = -75 mA ⁽¹⁾ | 5.5 V | | | | | 3.85 | | | |
| V _{OL} | I _{OL} = 50 μA | 4.5 V | 0.001 | | 0.1 | 0.1 | | 0.1 | V | |
| | | 5.5 V | 0.001 | | 0.1 | 0.1 | | 0.1 | | |
| | I _{OL} = 24 mA | 4.5 V | 0.36 | | | 0.5 | 0.44 | | | |
| | | 5.5 V | 0.36 | | | 0.5 | 0.44 | | | |
| | I _{OL} = 75 mA ⁽¹⁾ | 5.5 V | | | | | 1.65 | | | |
| I _{OZ} | V _O = V _{CC} or GND | 5.5 V | ±0.25 | | | ±5 | | ±2.5 | μA | |
| I _I | V _I = V _{CC} or GND | 5.5 V | ±0.1 | | | ±1 | | ±1 | μA | |
| I _{CC} | V _I = V _{CC} or GND, I _O = 0 | 5.5 V | 4 | | | 80 | | 40 | μA | |
| ΔI _{CC} ⁽²⁾ | One input at 3.4 V, Other inputs at GND or V _{CC} | 5.5 V | 0.6 | | | 1.6 | | 1.5 | mA | |
| C _i | V _I = V _{CC} or GND | 5 V | 2.5 | | | | | | pF | |
| C _o | V _I = V _{CC} or GND | 5 V | 8 | | | | | | pF | |

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

(2) This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see [Figure 1](#))

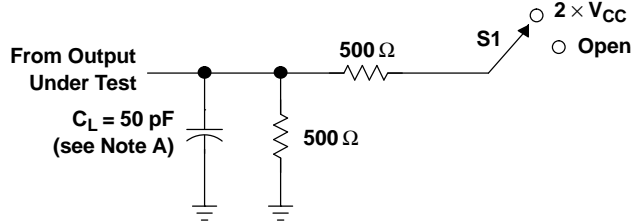
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | T _A = 25°C | | | SN74ACT244M-EP | | SN74ACT244I-EP | | UNIT |
|------------------|-----------------|-------------|-----------------------|-----|-----|----------------|------|----------------|------|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t _{PLH} | A | Y | 2 | 6.5 | 9 | 1 | 10 | 1.5 | 10 | ns |
| t _{PHL} | | | 2 | 7 | 9 | 1 | 10 | 1.5 | 10 | |
| t _{PZH} | \overline{OE} | Y | 1.5 | 7 | 8.5 | 1 | 9.5 | 1 | 9.5 | ns |
| t _{PZL} | | | 2 | 7 | 9.5 | 1 | 11 | 1.5 | 10.5 | |
| t _{PHZ} | \overline{OE} | Y | 2 | 8 | 9.5 | 1 | 11 | 1.5 | 10.5 | ns |
| t _{PLZ} | | | 2.5 | 7.5 | 10 | 1 | 11.5 | 2 | 10.5 | |

Operating Characteristics

V_{CC} = 5 V, T_A = 25°C

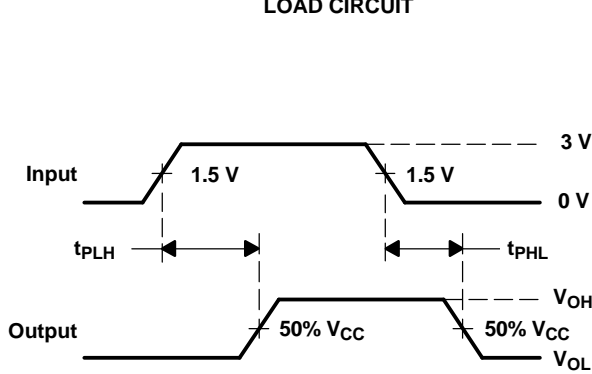
| PARAMETER | TEST CONDITIONS | TYP | UNIT |
|---|-----------------------------------|-----|------|
| C _{pd} Power dissipation capacitance | C _L = 50 pF, f = 1 MHz | 45 | pF |

PARAMETER MEASUREMENT INFORMATION

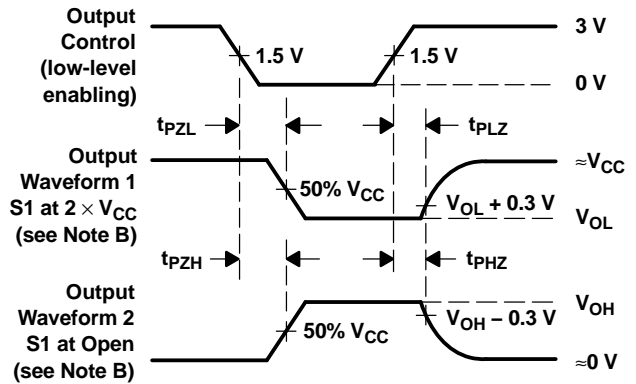


| TEST | S1 |
|-------------------|-------------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | $2 \times V_{CC}$ |
| t_{PHZ}/t_{PZH} | Open |

LOAD CIRCUIT



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
D. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| SN74ACT244IDWREP | ACTIVE | SOIC | DW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | SACT244IEP | Samples |
| SN74ACT244MDWREP | ACTIVE | SOIC | DW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | SACT244MEP | Samples |
| SN74ACT244MNSREP | ACTIVE | SO | NS | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | SACT244MEP | Samples |
| V62/04620-01XE | ACTIVE | SOIC | DW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | SACT244MEP | Samples |
| V62/04620-01YE | ACTIVE | SO | NS | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | SACT244MEP | Samples |
| V62/04620-02XE | ACTIVE | SOIC | DW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | SACT244IEP | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74ACT244-EP :

- Catalog: [SN74ACT244](#)

- Automotive: [SN74ACT244-Q1](#)

- Military: [SN54ACT244](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74ACT244IDWREP | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.3 | 2.7 | 12.0 | 24.0 | Q1 |
| SN74ACT244MDWREP | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.3 | 2.7 | 12.0 | 24.0 | Q1 |
| SN74ACT244MNSREP | SO | NS | 20 | 2000 | 330.0 | 24.4 | 8.4 | 13.0 | 2.5 | 12.0 | 24.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74ACT244IDWREP | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| SN74ACT244MDWREP | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| SN74ACT244MNSREP | SO | NS | 20 | 2000 | 367.0 | 367.0 | 45.0 |

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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